

PCN Number:	20160719000		PCN Date:	07/21/2016	
Title:	DLPC343X and DLPC150 Alternate Assembly Location				
Customer Contact:	Dlp-pcn-team@list.ti.com		Dept:	DLP® CQE	
Proposed 1st Ship Date:	10/21/2016		Estimated Sample Availability:	09/16/2016	
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
IC supplier qualified alternate assembly site for the devices listed in 'Product Affected' section below.					
	Current Location	New Location			
Assembly Location	Amkor, Philippines	ASE ChungLi, Taiwan			
Reason for Change:					
Lead time improvement and robustness of supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
None					
Product Affected:					
DLPC3430CZVBR, DLPC3433CZVB, DLPC3435CZEZ, DLPC3437CZEZ, DLPC3438CZEZ, DLPC3439CZEZ, DLPC3440CZEZ, DLPC150ZEZ					
Qualification Data					
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.					
Qual Vehicle: DLPC3430CZVBR, DLPC3438CZEZ					
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Test	Sample Size			Results	
Wafer Thickness	3 Points			Pass	
Wafer Mount	1 Wafer/Wafer Lot, 20 Units/Wafer			Pass	
Wafer Saw	1 Wafer/Wafer Lot, 20 Units/Wafer			Pass	
Kerf Width	1 Wafer/Wafer Lot, 5 Units/Wafer			Pass	
2/O QA GATE	Every Wafer, 30 Units/Wafer			Pass	
Die Attach	3 Strips/Mag			Pass	
Visual	4 Units/Lot			Pass	
Die Shear	5 Units/Lot			Pass	
Epoxy Coverage	5 Units/Lot			Pass	
Epoxy Fillet Height	5 Units/Lot			Pass	
Epoxy Void	5 Units/Lot			Pass	
Epoxy Thickness	30 Dies/Lot, 1 Reading/Die			Pass	

Wire Bond	4 Strips/Mag(DLPC3438); 3 Strips/Mag (DLPC3430)	Pass
Visual	8 Wires	Pass
Loop Height Measurement	2 Units/Lot, 16 Wires/Unit	Pass
Wire Pull	2 Units/Lot, 16 Wires/Unit	Pass
Ball Shear	2 Units/Lot, 22 Balls/Unit	Pass
Ball Size(X)	1 Units/Lot, 22 Balls/Unit	Pass
Ball Size(Y)	1 Units/Lot, 22 Balls/Unit	Pass
Ball Thickness(Z)	1 Unit/Lot, 10 Balls/Unit	Pass
Cratering	3 Units/ Lot	Pass
3/O QA Gate	90 Units/Lot	Pass
Molding		Pass
Visual	1 Chase/Lot	Pass
X-Ray	AQL=0.04%	Pass
X-Ray Internal Void	3 Units/Lot	Pass
X-Ray Wire Sweep	30 Units/Lot, 1 Wire/Unit	Pass
T-Side Mark		Pass
Visual	5 Strips/Lot	Pass
M.P.T Test	NA	Pass
Ball Mount		Pass
Visual Inspection	1ST Strip/Lot	Pass
Solder Ball Shear	1 Unit/Lot, 10 Balls/Unit	Pass
Form/ Singulation		Pass
Visual	1ST Strip/Lot	Pass
SAT Test	5 Units/Lot	Pass
Coplanarity	1 Tray/Lot	Pass
Package Dimension	5 Units	Pass
Unit Weight	30 Units/Lot	Pass
Outgoing QA Gate	AQL=0.04%	Pass

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
DLP® Products	Dlp-pcn-team@list.ti.com
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com